



AG PASTE FOR POWER ELECTRONICS

AG SINTERING PASTE CHARACTERISTICS

Ag sintering paste		
Conductive filler	Silver	
Ag contents (wt%) @ paste	78-87	
Density	3.5-4.0	- Thermal pressure sintering - Sintering condition : 250°C/2-5min, 5-15MPa - High heat dissipation - Optimized for Ag/Au surface
Thermal conductivity (W/mk)	> 200	
Shear strength (MPa) @ 5mm x 5mm	> 40	
Viscosity (kcps, shear rate 10, @25°C)	28±2	

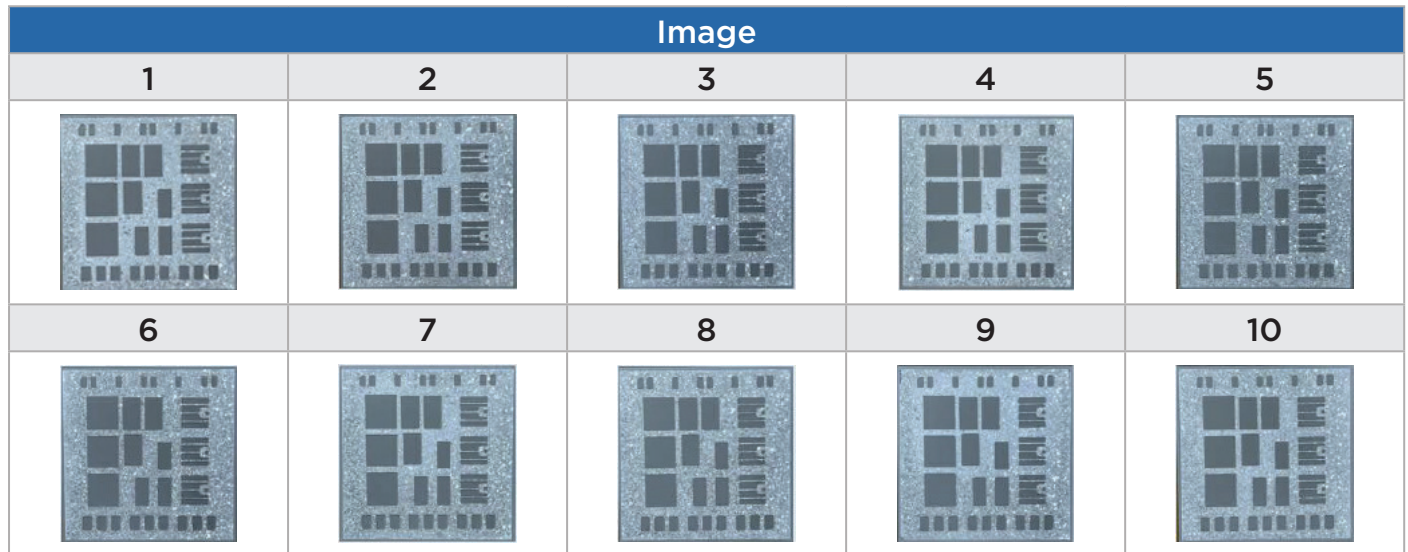


Ag sintering paste for printing

STENCIL LIFE

Test method

: Printing 10 substrates after printing 300 times -> no dent / bridge



GATE PAD THICKNESS AFTER DRYING

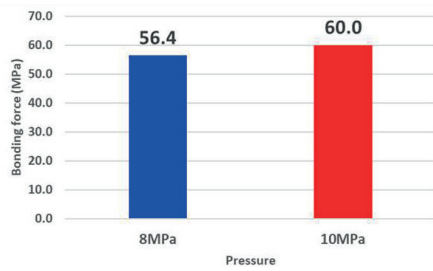
: Mask thickness 0.2mm

: Drying conditions -130°C, 20 min

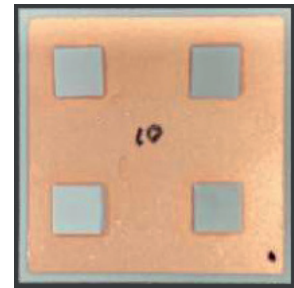
	1Point	2Point	3Point
1	164	168	168
2	166	169	162
3	172	172	165
4	165	168	172
5	166	168	166
6	162	169	165
7	158	166	162
8	155	154	158
9	164	160	158
10	161	160	164



SINTERING _ AG DEPOSITED AMB SUBSTRATE

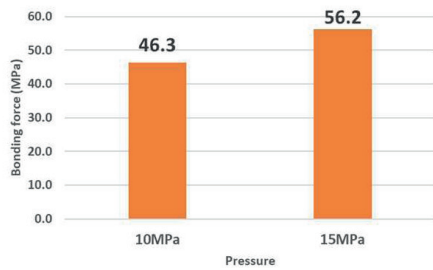


- ✓ Sintering temperature : 250°C
- ✓ Sintering time : 150 sec
- ✓ Chip surface finish : Au
- ✓ Chip size : 5*5mm

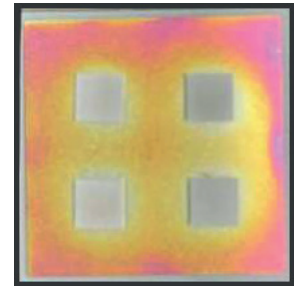


After drying

SINTERING _ BARE AMB SUBSTRATE



- ✓ Drying conditions : 130°C, 30min, under N₂
- ✓ Sintering conditions : 280°C, 180sec, in Air
- ✓ Chip surface finish : Au
- ✓ Chip size : 5*5mm



After sintering

